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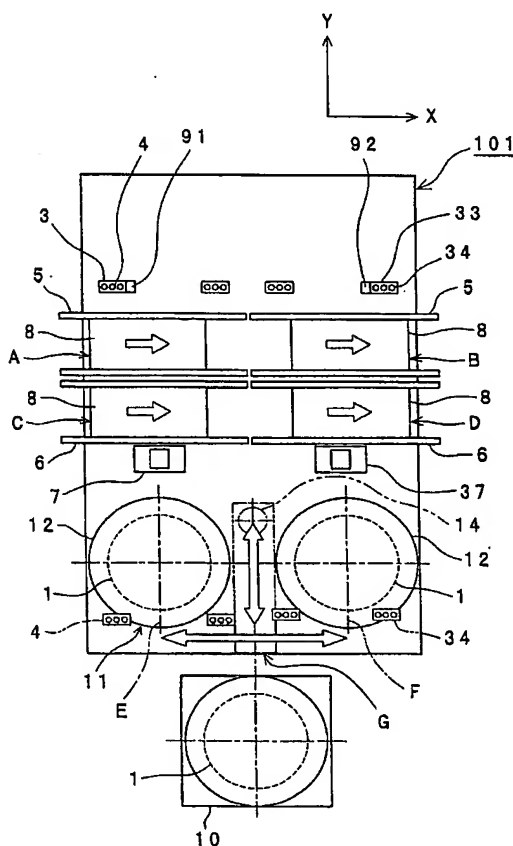
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(54) Title: COMPONENT MOUNTING APPARATUS AND COMPONENT MOUNTING METHOD



(57) Abstract: A component mounting apparatus (101) is provided with a board holding device (5, 6) for holding a board (8) at a board holding position (A, B, C and D), a first mounting head (4) for holding and taking out a component (2) fed from a first component feeding position (E) and mounting the component on the board held at the board holding position, a second mounting head (34) for holding and taking out the component fed from a second component feeding position (F) and mounting the component on the held board, and a component feeding device (11) having a wafer holding table (12) for holding a wafer (1) on which the respective components are fed so that the wafer holding table can be moved reciprocally between the first component feeding position and the second component feeding position.

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